



MB1-130-01-F-S-01-SL

MB1-130-01-F-S-01-SL-N

(1.00 mm) .0394"

MB1 SERIES

MINI EDGE CARD SOCKET WITH GUIDES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MB1

Insulator Material:

Black LCP

Contact Material:

BeCu

Plating:

Sn or Au over

50 μ " (1.27 μ m) Ni

Current Rating:

2.4 A per pin

(2 pins powered)

Voltage Rating:

250 VDC/354 VDC

Operating Temp Range:

-55 °C to +125 °C

Insertion Depth:

(5.26 mm) .207" to

(6.10 mm) .240"

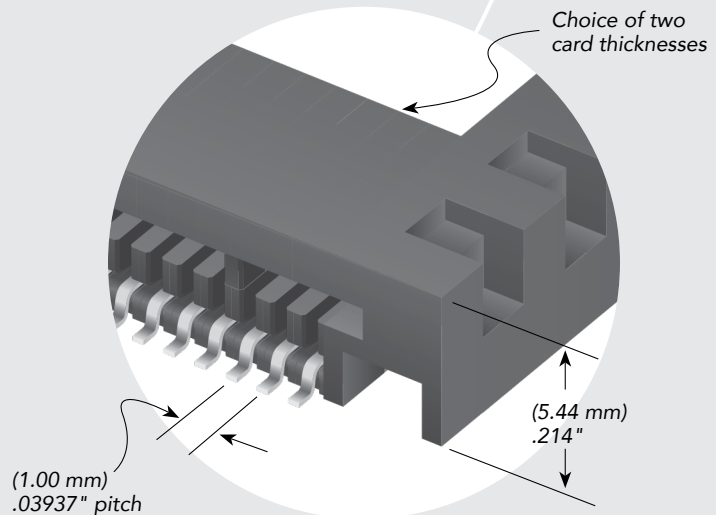
RoHS Compliant:

Yes

Mates with:

(0.80 mm) .031" PCB,

(1.60 mm) .062" PCB



PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (20-30)

(0.15 mm) .006" max (40-50)*

*(.004" stencil solution

may be available; contact

ipg@samtec.com)

RECOGNITIONS

For complete scope of

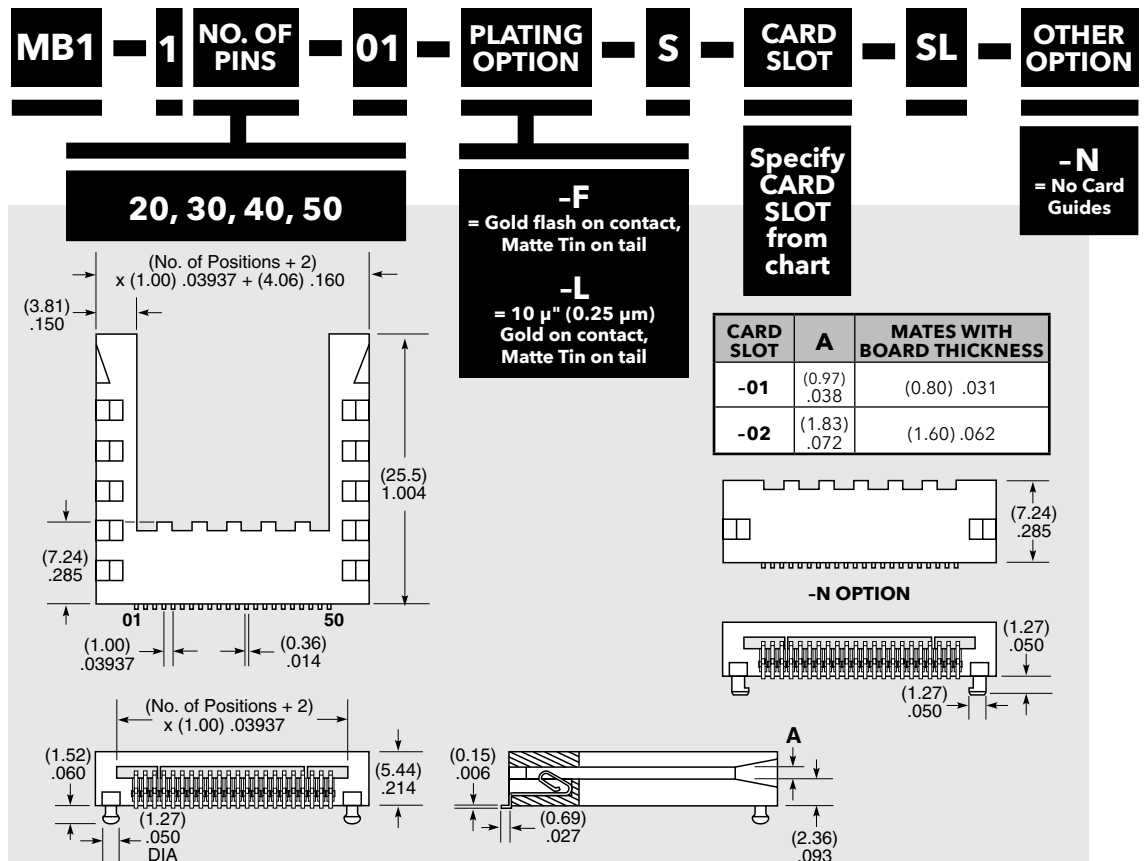
recognitions see

www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- Other platings



Important Note: Samtec recommends that pads on the mating board be Gold plated.

WWW.SAMTEC.COM

Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.